

Description

The AO4406A uses advanced trench technology

to provide excellent R_{DS(ON)}, low gate charge and

operation with gate voltages as low as 4.5V. This

device is suitable for use as a

Battery protection or in other Switching application.

D S S S

SOP-8

General Features

 $V_{DS} = 30V I_{D} = 13A$

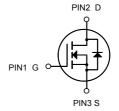
 $R_{DS(ON)}$ < 13m Ω @ V_{GS} =10V

Application

Battery protection

Load switch

Uninterruptible power supply



N-Channel MOSFET

Package Marking and Ordering Information

Product ID	Pack	Brand	Qty(PCS)
AO4406A	SOP-8	HXY MOSFET	3000

Absolute Maximum Ratings (TA=25°C unless otherwise noted)

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	30	V
Vgs	Gate-Source Voltage	±20	V
In@T _A =25°C	Continuous Drain Current ¹	13	А
ID@TA=70°C	Continuous Drain Current ¹	7	А
Ідм	Pulsed Drain Current ²	41	Α
EAS	Single Pulse Avalanche Energy ³	15	mJ
P _D @T _A =25°C	Total Power Dissipation ⁴	12	W
Тѕтс	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range -55 to 150		°C
_	Thermal Resistance Junction-ambient¹(t≤10s)	85	°C/W
R _θ JA	Thermal Resistance Junction-ambient ¹	25	°C/W



Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	30			V	
△BV _{DSS} /△T _J	BVDSS Temperature Coefficient	Reference to 25°C , I _D =1mA		0.034		V/°C	
D	Static Drain-Source On-Resistance ²	V _{GS} =10V , I _D =7A	9.5 13		13	0	
R _{DS(ON)}	Static Drain-Source On-Resistance-	V _{GS} =4.5V , I _D =4A		15	19	mΩ	
V _{GS(th)}	Gate Threshold Voltage	V -V 1 -250A	1.2	1.4	2.5	V	
$\triangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	$V_{GS}=V_{DS}$, $I_D=250uA$		-3.84		mV/°C	
,	Danier Courses I and a second	V _{DS} =24V , V _{GS} =0V , T _J =25°C			1		
IDSS	Drain-Source Leakage Current	V _{DS} =24V , V _{GS} =0V , T _J =55°C			5	uA	
Igss	Gate-Source Leakage Current	V _{GS} =±20V , V _{DS} =0V			±100	nA	
gfs	Forward Transconductance	V _{DS} =5V , I _D =7A		6.2		S	
Rg	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		1.04	2.1	Ω	
Qg	Total Gate Charge (4.5V)			6	8.4		
Q_{gs}	Gate-Source Charge	V _{DS} =15V , V _{GS} =4.5V , I _D =7A		2.2	3.1	nC	
Q_{gd}	Gate-Drain Charge			2	2.8		
$T_{d(on)}$	Turn-On Delay Time			1.2	2.4		
Tr	Rise Time	V_{DD} =15V , V_{GS} =10V , R_{G} =3.3 Ω		40	72.0		
T _{d(off)}	Turn-Off Delay Time	I _D =7A		18	36.0	ns	
T _f	Fall Time			7.2	14.4		
Ciss	Input Capacitance			783	1316		
Coss	Output Capacitance	V _{DS} =15V , V _{GS} =0V , f=1MHz		127	167.8	pF	
Crss	Reverse Transfer Capacitance			89	122.6		

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current ^{1,5}	\/0\/ Force Current			7	Α
I _{SM}	Pulsed Source Current ^{2,5}	₃=V _D =0V , Force Current			35	Α
V _{SD}	Diode Forward Voltage ² V _G	_{3S} =0V , I _S =1A , T _J =25°C			1.2	V
t _{rr}	Reverse Recovery Time			7.2		nS
Qrr	Reverse Recovery Charge	=7A , dl/dt=100A/µs , T _J =25°C		2.9		nC

Note:

- 1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\,\leq\,300\text{us}$, duty cycle $\,\leq\,2\%$
- 3. The EAS data shows Max. rating . The test condition is V_{DD} =25V, V_{GS} =10V, L=0.1mH, I_{AS} =20A
- 4. The power dissipation is limited by 150°C junction temperature
- 5. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



Typical Characteristics

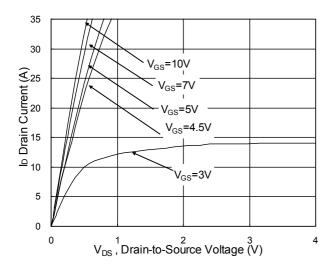


Fig.1 Typical Output Characteristics

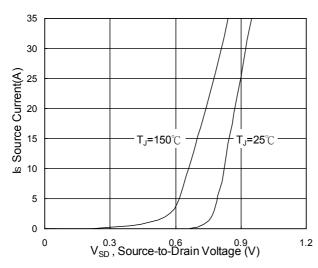


Fig.3 Forward Characteristics Of Reverse

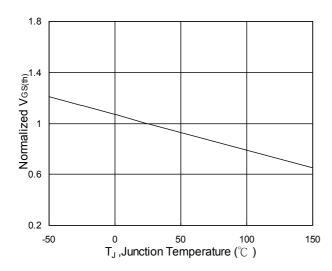


Fig.5 Normalized V_{GS(th)} vs. T_J

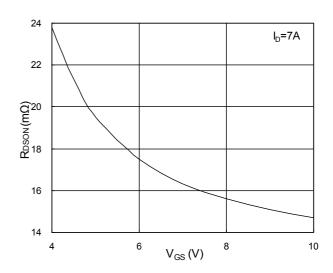


Fig.2 On-Resistance vs. Gate-Source

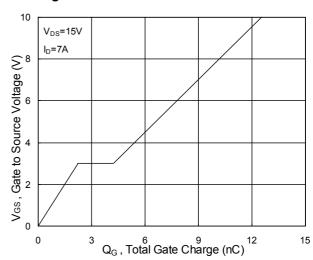


Fig.4 Gate-Charge Characteristics

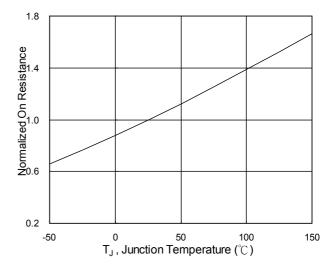
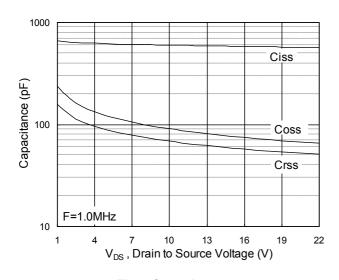


Fig.6 Normalized R_{DSON} vs. T_J



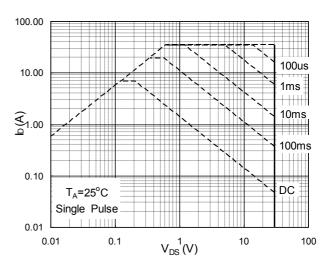


Fig.7 Capacitance

Fig.8 Safe Operating Area

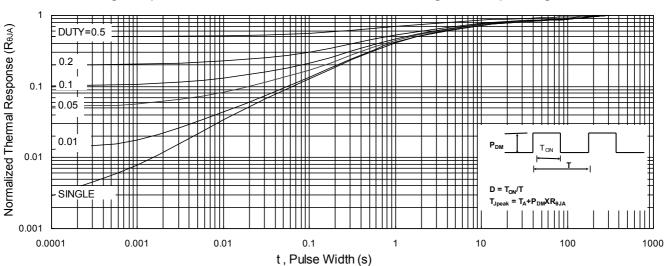


Fig.9 Normalized Maximum Transient Thermal Impedance

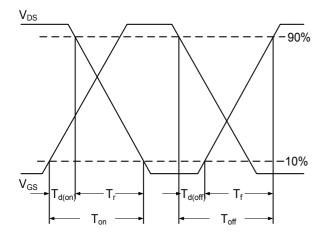


Fig.10 Switching Time Waveform

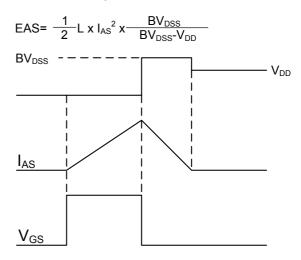
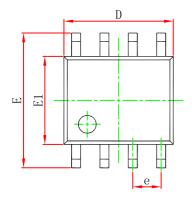
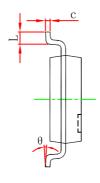


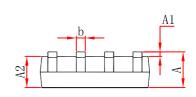
Fig.11 Unclamped Inductive Switching Waveform



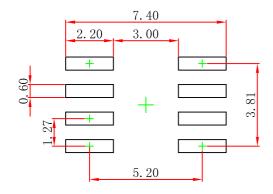
SOP-8 Package Outline Dimensions







Symbol	Dimensions In Millimeters		Dimensions In Inches		
3y111001	Min	Max	Min	Max	
A	1.350	1.750	0.053	0.069	
A1	0.100	0.250	0.004	0.010	
A2	1.350	1.550	0.053	0.061	
b	0.330	0.510	0.013	0. 020	
c	0.170	0.250	0.007	0.010	
D	4.800	5.000	0.189	0.197	
e	1. 270 (BSC)		0.050 (BSC)		
E	5.800	6. 200	0.228	0.244	
E1	3.800	4.000	0.150	0.157	
L	0.400	1.270	0.016	0.050	
θ	0°	8°	0°	8°	



- Note: 1.Controlling dimension:in millimeters.
- 2.General tolerance:± 0.05mm.
 3.The pad layout is for reference purposes only.



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